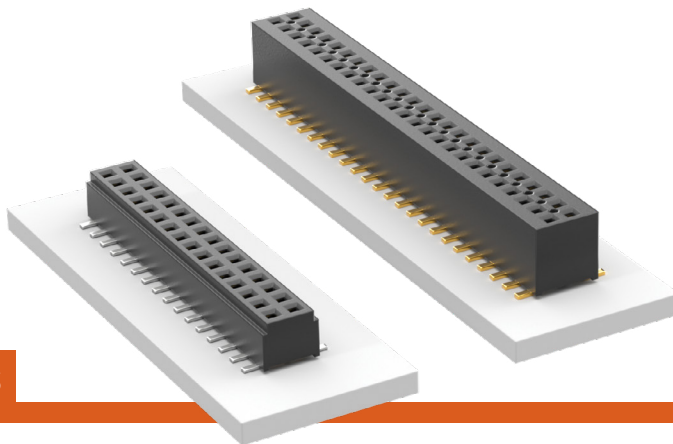


RUGGED RELIABLE MICRO SOCKETS

(1.00 mm) .0394" PITCH • CLM/MLE SERIES



CLM

Mates:

FTM, FTMH, MW

MLE

Mates:

FTM, FTMH, MW

SPECIFICATIONS

Insulator Material: Black LCP

Contact Material:

CLM: Phosphor Bronze

MLE: BeCu

Plating:

CLM: Au or Sn over

50 μ " (1.27 μ m) Ni

MLE: Au over 10 μ " (0.25 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Current Rating (CLM/FTMH):

3.1 A per pin

(2 pins powered)

Current Rating (MLE/FTMH):

2.9 A per pin (2 pins powered)

Max Cycles:

CLM: 100 with 10 μ " (0.25 μ m) Au

Voltage Rating:

CLM: 270 VAC/382 VDC

MLE: 310 VAC/438 VDC

Insertion Depth:

CLM:

Top Entry = (1.40 mm) .055" min.,

Bottom Entry =

(2.41 mm) .095" min.

(Add board thickness for

correct post OAL)

MLE:

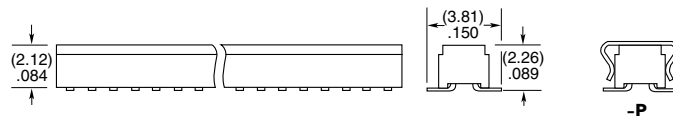
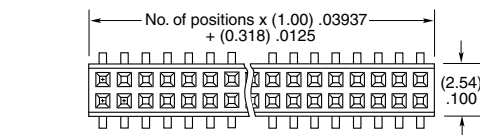
(1.63 mm) .064" to

(3.18 mm) .125" with

(0.38 mm) .015" wipe,

pass-through, or (2.44 mm) .096"

minimum for bottom entry



MLE

1

NO. PINS
PER ROW

01

PLATING
OPTION

DV

OPTIONS

02 thru 50

-G

= 10 μ "
(0.25 μ m)
Gold

-A

= Alignment Pin
(3 positions minimum)
Metal or plastic
at Samtec discretion

-K

= (4.00 mm) .1575" DIA
Polyimide film
Pick & Place Pad
(5 positions minimum)

-P

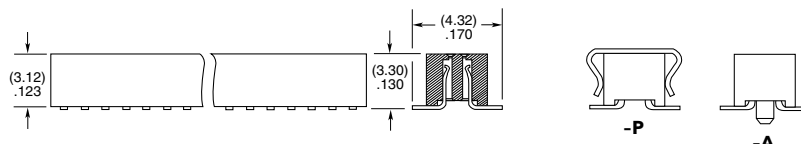
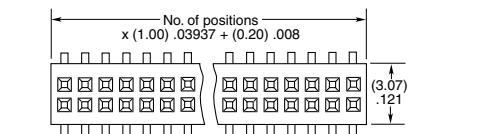
= Metal Pick & Place Pad
(5 positions minimum)

-TR

= Tape & Reel

-FR

= Full Reel Tape & Reel
(must order maximum
quantity per reel;
contact Samtec for
quantity breaks)



PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

ALSO AVAILABLE

Contact Samtec

Alignment pin

Other Gold plating options



Note:

Some lengths, styles and
options are non-standard,
non-returnable.